

## FL2012M

*No Clean Liquid Flux*



### Product Description

FL2012M is a RMA flux, which has the same fluxing mechanism as a pure rosin flux but with enhanced cleaning ability. This flux has been formulated such that no solder balls are formed and bridging problems are minimised. The flux leaves a thin transparent coat, which not only protects the board surface but also gives it additional aesthetic values.

### Application

FL2012M is specially formulated for spraying, foaming processes and can also suitable for dipping applications. On board preheat temperature is recommended to be 80 – 100 °C.

### Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

### Recommended Solvent

Asahi's complementary Solvent S2012M. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

### Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

### Storage

Under proper storage condition, FL2012M can be stored for up to 6 months. FL2012M is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

### Packaging

Available in 18kg/carboy.

### Specification

Item	Result
State	Liquid
Colour	Transparent yellow
Specific Gravity @ 25°C	0.810 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	10.0 +/- 1.0 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	0.08 +/- 0.01 wt%
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	27.0 +/- 2.0 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 <sup>4</sup> Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
<small>JIS Z 3197 8.5.3</small>	
Electromigration (85°C, 88.5%RH, 596hrs)	> 1 x 10 <sup>11</sup> Ω, Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROM1
<small>IPC J-STD-004</small>	
Spread Factor	> 85% (SnPb)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Matte

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